

# William J Song

## List of Publications by Year in descending order

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Version: 2024-02-01

22  
papers

982  
citations

1307594

7  
h-index

1199594

12  
g-index

22  
all docs

22  
docs citations

22  
times ranked

855  
citing authors

#	ARTICLE	IF	CITATIONS
1	Thread-Aware Area-Efficient High-Level Synthesis Compiler for Embedded Devices. , 2021, , .		0
2	Hardware accelerator systems for embedded systems. Advances in Computers, 2021, 122, 23-49.	1.6	3
3	Energy-Efficient Acceleration of Deep Neural Networks on Realtime-Constrained Embedded Edge Devices. IEEE Access, 2020, 8, 216259-216270.	4.2	15
4	The Nebula Benchmark Suite: Implications of Lightweight Neural Networks. IEEE Transactions on Computers, 2020, , 1-1.	3.4	3
5	Duplo: Lifting Redundant Memory Accesses of Deep Neural Networks for GPU Tensor Cores. , 2020, , .		10
6	FineReg: Fine-Grained Register File Management for Augmenting GPU Throughput. , 2018, , .		9
7	Reliability-performance tradeoffs between 2.5D and 3D-stacked DRAM processors. , 2016, , .		2
8	Measurement-Driven Methodology for Evaluating Processor Heterogeneity Options for Power-Performance Efficiency. , 2016, , .		1
9	Amdahl's law for lifetime reliability scaling in heterogeneous multicore processors. , 2016, , .		6
10	KitFox: Multiphysics Libraries for Integrated Power, Thermal, and Reliability Simulations of Multicore Microarchitecture. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1590-1601.	2.5	7
11	Managing performance-reliability tradeoffs in multicore processors. , 2015, , .		8
12	Architectural Reliability: Lifetime Reliability Characterization and Management of Many-Core Processors. IEEE Computer Architecture Letters, 2015, 14, 103-106.	1.5	20
13	Power Modeling for GPU Architectures Using McPAT. ACM Transactions on Design Automation of Electronic Systems, 2014, 19, 1-24.	2.6	54
14	Energy Introspector: A parallel, composable framework for integrated power-reliability-thermal modeling for multicore architectures. , 2014, , .		8
15	Manifold: A parallel simulation framework for multicore systems. , 2014, , .		52
16	Control Principles and On-Chip Circuits for Active Cooling Using Integrated Superlattice-Based Thin-Film Thermoelectric Devices. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2014, 22, 1909-1919.	3.1	8
17	Post-Silicon Characterization and On-Line Prediction of Transient Thermal Field in Integrated Circuits Using Thermal System Identification. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 37-45.	2.5	3
18	Enhancements to FPMIPv6 for improved seamless vertical handover between LTE and heterogeneous access networks. IEEE Wireless Communications, 2013, 20, 112-119.	9.0	15

#	ARTICLE	IF	CITATIONS
19	SST: A Scalable Parallel Framework for Architecture-Level Performance, Power, Area and Thermal Simulation. Computer Journal, 2012, 55, 181-191.	2.4	5
20	Thermal system identification (TSI): A methodology for post-silicon characterization and prediction of the transient thermal field in multicore chips. , 2012, , .		9
21	A framework for architecture-level power, area, and thermal simulation and its application to network-on-chip design exploration. Performance Evaluation Review, 2011, 38, 63-68.	0.6	24
22	Improvements to seamless vertical handover between mobile WiMAX and 3GPP UTRAN through the evolved packet core. IEEE Communications Magazine, 2009, 47, 66-73.	6.1	720